IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re Application of:

Wei-Yung Hsu, et al.

Serial No.: 10/792.069

Confirmation No : 4228

Filed: March 3, 2004

For:

Integrated Multi-Step Gap Fill and Feature

Planarization for

Conductive Materials

MAIL STOP AMENDMENT Commissioner for Patents P O Box 1450

Alexandria, VA 22313-1450

Dear Sir:

Group Art Unit: 1742

Examiner:

William T. Leader

CERTIFICATE OF TRANSMISSION

I hereby certify that this correspondence is being electronically transmitted to the U.S. Patent and Trademark Office via EFS-Web to the attention of Examiner William T. Leader, on the date shown below.

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Date

Keith M Tackett

RESPONSE TO OFFICE ACTION DATED APRIL 3, 2007

In response to the Office Action dated April 3, 2007, having a shortened statutory period for response extended one month and set to expire on August 3, 2007, please enter this response and reconsider the claims pending in the application for the reasons discussed below. Payment of fees for the one month extension is authorized on a separate fee transmittal. Although Applicants believe that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/005614.D1/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper. Remarks begin on page 5 of this paper.